

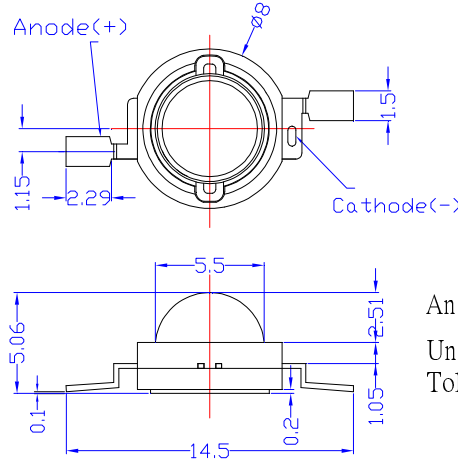
■Features

- Highest luminous flux
- Super energy efficiency
- Very long operating life
- Superior ESD protection

■Applications

- Night Vision
- Camera
- Outdoor./Indoor applications

■Outline Dimension



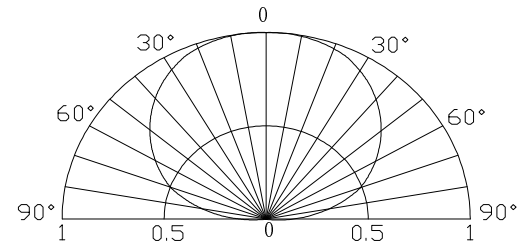
■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value	Unit
DC Forward Current	I _F	1000	mA
Pulse Forward Current*	I _{FP}	2000	mA
Reverse Voltage	V _R	5	V
Power Dissipation	P _D	1700	mW
Operating Temperature	Topr	-30 ~ +85	°C
Storage Temperature	Tstg	-40~ +100	°C
Lead Soldering Temperature	Tsol	260°C/5sec	-

*Pulse width Max.10ms Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward Voltage	V _F	I _F =350mA	-	1.5	1.7	V
DC Reverse Current	I _R	V _R =5V	-	-	10	μA
Peak Wavelength	λ _P	I _F =350mA	-	850	-	nm
Radiant Power	P _O	I _F =350mA	110	-	-	mW
50% Power Angle	2θ _{1/2}	I _F =350mA	-	140	-	deg

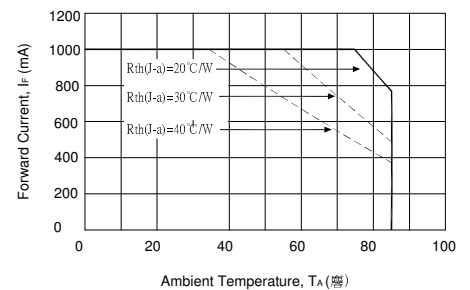
*1 Tolerance of measurements of peak wavelength is ±1nm

*2 Tolerance of measurements of radiant power is ±15%

*3 Tolerance of measurements of forward voltage is ±0.1V

Note: Advises please attach heat sink to use if Power Dissipation is more than 0.5W.

■Forward Operating Current (DC)



■ **Soldering Heat Reliability :**

Reflow soldering Profile

- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the **characteristics of the LEDs will or will not be damaged by repairing.**

Solder
Average ramp-up rate = 3°C/sec. max.
Preheat temperature: 150°~180°C
Preheat time = 120 sec. max.
Ramp-down rate = 6°C/sec. max.
Peak temperature = 220°C max.
Time within 3°C of actual peak temperature = 25 sec. max.
Duration above 200°C is 40 sec. max.

